

1.6x0.8mm SMD CHIP LED LAMP

#### **Features**

• Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

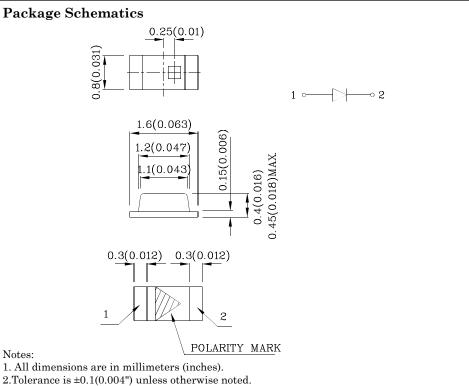
ullet Package : 2000pcs / reel

• Moisture sensitivity level : level 3

• RoHS compliant







3.	Specifications	are subject	t to change	without notice.
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Absolute Maximum Ratings (T <sub>A</sub> =25°C)	MGT (GaP)	Unit		
Reverse Voltage	$V_{\mathrm{R}}$	5	V	
Forward Current	$I_{\mathrm{F}}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	$P_{D}$	62.5	mW	
Operating Temperature	$T_{A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		

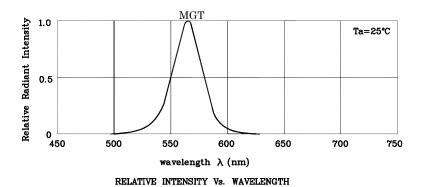
Operating Characteristics (T <sub>A</sub> =25°C)		MGT (GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.2	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{ m F}$	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_R$	10	uA
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λР	565	nm
Wavelength of Dominant Emission (Typ.) (I <sub>F</sub> =20mA)	λD	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	pF

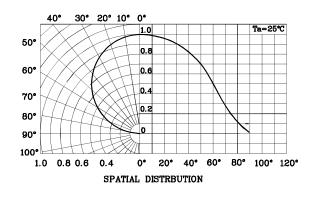
Part Number	Emitting Color	Emitting Material	Lens-color	In (I <sub>F</sub> =	minous tensity =20mA) mcd	Wavelength nm λP	Viewing Angle 2θ 1/2
				min.	typ.		
XZMGT53W-3	Green	GaP	Water Clear	8	14	565	120°

Apr 23,2011 XDSA7251 V5 Layout: Maggie L.

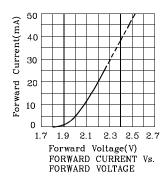


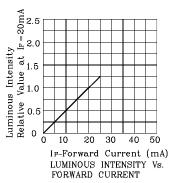


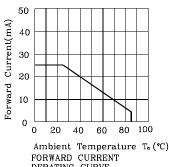


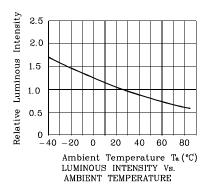


## **♦** MGT



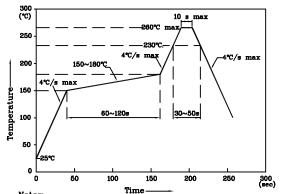






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

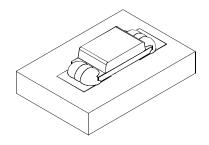


- Notes:
  1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

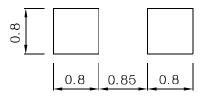




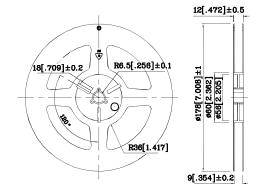
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



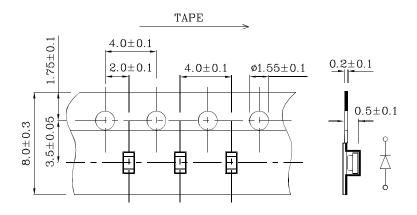
**❖** Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



## **❖** Reel Dimension



## **❖** Tape Specification (Units:mm)



# Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Apr 23,2011

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## PACKING & LABEL SPECIFICATIONS

